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5. A method of fabricating a semiconductor structure as claimed in claim 4 wherein the step of forming by atomic layer deposition a monocrystalline seed layer further includes the step of desorbing the layer of hydrogen formed on the substrate, exposing the silicon substrate to a silicon precursor and at least one metal precursor thereby forming a layer of a silicon and a metal on the surface of the silicon substrate, flushing the layer of silicon with an inert gas to remove any excess silicon and metal precursor material, exposing the surface of the layer of silicon to at least one of oxygen (O_2) with or without plasma, water (H_2O), nitrous oxide (N_2O), or nitric oxide (NO) to oxidize the layer of silicon and metal thereby forming a single oxidized monolayer, and flushing the oxidized monolayer with an inert gas.

6. A method of fabricating a semiconductor structure as claimed in claim 5 further including the step of repeating the atomic layer deposition to form monolayers.

7. A method of fabricating a semiconductor structure as claimed in claim 1 whereby the step of forming by atomic layer deposition one or more layers of a monocrystalline high dielectric constant oxide includes the steps of exposing the seed layer to a metal precursor, thereby forming a layer of metal, flushing the layer of metal with

an inert gas, exposing the layer of metal to at least one of oxygen (O) with or without plasma, water (H₂O), nitrous oxide (N₂O), or nitric oxide (NO) to oxidize the layer of metal thereby forming a single high-k oxidized monolayer, and flushing the oxidized monolayer with an inert gas.

8. A method of fabricating a semiconductor structure as claimed in claim 7 further including the step of repeating the atomic layer deposition to form a monocrystalline high-k oxide layer of a desired thickness.

9. A method of fabricating a semiconductor structure comprising the steps of:

providing a silicon substrate having a surface;

forming by atomic layer deposition a monocrystalline seed layer on the surface of the silicon substrate, the seed layer formed of a silicate material; and

forming by atomic layer deposition one or more layers of a monocrystalline high dielectric constant oxide on the seed layer.

10. A method of fabricating a semiconductor structure as claimed in claim 9 wherein the step of forming by atomic layer deposition the seed layer of a silicate material includes forming the seed layer of a silicate material selected from the group of strontium silicon oxide (SrSiO_4), zirconium silicon oxide (ZrSiO_4), and hafnium silicon oxide (HfSiO_4).

11. A method of fabricating a semiconductor structure as claimed in claim 10 wherein the step of forming by atomic layer deposition one or more layers of a monocrystalline high dielectric constant oxide on the seed layer includes forming the layer of high dielectric constant oxide selected from the group of hafnium oxide (HfO_2), zirconium oxide (ZrO_2), strontium titanate (SrTiO_3), lanthanum oxide (La_2O_3), yttrium oxide (Y_2O_3), titanium oxide (TiO_2), barium titanate (BaTiO_3), lanthanum aluminate (LaAlO_3), lanthanum scandium oxide (LaScO_3) and aluminum oxide (Al_2O_3).

12. A method of fabricating a semiconductor structure as claimed in claim 11 wherein the step of providing a substrate includes the step of providing a substrate having formed thereon a silicon oxide.

13. A method of fabricating a semiconductor structure as claimed in claim 12 wherein the step of forming by atomic layer deposition a monocrystalline seed layer further includes the step of depositing a layer of a metal oxide onto a surface of the silicon oxide, flushing the layer of metal oxide with an inert gas, reacting the metal oxide with the silicon oxide to form the silicate selected from the group of strontium silicon oxide (SrSiO_4), zirconium silicon oxide (ZrSiO_4), and hafnium silicon oxide (HfSiO_4).

14. A method of fabricating a semiconductor structure as claimed in claim 11 wherein the step of providing a substrate includes providing a substrate having a layer of hydrogen formed thereon by hydrogen passivation.

15. A method of fabricating a semiconductor structure as claimed in claim 14 wherein the step of forming by atomic layer deposition a seed layer further includes the step of desorbing the layer of hydrogen formed on the substrate, exposing the silicon substrate to a silicon precursor and at least one metal precursor forming a layer of a silicon and a metal on the surface of the silicon substrate, flushing the layer of silicon with an inert gas to remove any excess silicon and metal precursor material, exposing the surface of the layer of silicon to at least one of oxygen (O_2) with or without plasma, water (H_2O), nitrous oxide (N_2O), or nitric oxide (NO) to oxidize the layer of silicon and metal thereby forming a single oxidized monolayer, and flushing the oxidized monolayer with an inert gas.

16. A method of fabricating a semiconductor structure as claimed in claim 15 further including the step of repeating the atomic layer deposition to form oxidized monolayers.

17. A method of fabricating a semiconductor structure as claimed in claim 11 whereby the step of forming by atomic layer deposition one or more layers of a monocrystalline high dielectric constant oxide includes the steps of exposing the monocrystalline seed layer to a metal precursor, thereby forming a layer of metal, flushing the layer of metal with an inert gas, exposing the layer of metal to at least one of oxygen (O) with or without plasma, water (H₂O), nitrous oxide (N₂O), or nitric oxide (NO) to oxidize the layer of metal thereby forming a single monocrystalline high-k oxidized monolayer, and flushing the oxidized monolayer with an inert gas.

18. A method of fabricating a semiconductor structure as claimed in claim 17 further including the step of repeating the atomic layer deposition to form monocrystalline high-k oxide of a desired thickness.

19. A method of fabricating a semiconductor structure comprising the steps of:

providing a silicon substrate having a surface;

forming by atomic layer deposition a monocrystalline seed layer on the surface of the silicon substrate, the seed layer formed of a silicate material selected from the group of strontium silicon oxide (SrSiO_4), zirconium silicon oxide (ZrSiO_4), and hafnium silicon oxide (HfSiO_4); and

forming by atomic layer deposition one or more layers of a monocrystalline high dielectric constant oxide on the seed layer, the layer of high dielectric constant oxide selected from the group of hafnium oxide (HfO_2), zirconium oxide (ZrO_2), strontium titanate (SrTiO_3), lanthanum oxide (La_2O_3), yttrium oxide (Y_2O_3), titanium oxide (TiO_2), barium titanate (BaTiO_3), lanthanum aluminate (LaAlO_3), lanthanum scandium oxide (LaScO_3) and aluminum oxide (Al_2O_3).

20. A method of fabricating a semiconductor structure as claimed in claim 19 wherein the step of providing a silicon substrate having a surface includes the step of providing one of a silicon substrate having formed thereon the surface a layer of silicon oxide or a layer of hydrogen formed by hydrogen passivation.